

Product Information Sheet

EPO-TEK® OE100-T

Date: December 2023
Rev: III
No. of Components: Two
Mix Ratio by Weight: 10 : 1
Specific Gravity: Part A: 1.12 Part B: 1.02
Pot Life: 3 Hours
Shelf Life- Bulk: One year at room temperature

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
 150°C / 1 Minute
 80°C / 30 Minutes

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- **TOTAL MASS SHOULD NOT EXCEED 25 GRAMS**

Product Description: A two component, high Tg, high temperature grade epoxy designed for semiconductor, underfill, hard-disk drive and hybrid micro-electronics packaging applications. The epoxy can also be used for adhesive and sealing applications in electronics, optical, and medical devices.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: White	Part B: Amber	
* Consistency:	Smooth Flowable Paste		
* Viscosity (23°C) @ 50 rpm:	4,500 - 7,000	cPs	
Thixotropic Index:	2.9		
* Glass Transition Temp:	≥ 100	°C	(Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	43	x 10 ⁻⁶ in/in°C
	Above Tg:	165	x 10 ⁻⁶ in/in°C
Shore D Hardness:	87		
Lap Shear @ 23°C:	> 2,000	psi	
Die Shear @ 23°C:	≥ 10	Kg	3,556 psi
Degradation Temp:	468	°C	
Weight Loss:			
	@ 200°C:	0.38	%
	@ 250°C:	0.50	%
	@ 300°C:	0.84	%
Suggested Operating Temperature:	< 350	°C	(Intermittent)
Storage Modulus:	244,296	psi	
* Particle Size:	≤ 10	microns	

ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:	N/A		
Volume Resistivity @ 23°C:	≥ 1 x 10 ¹³	Ohm-cm	
Dielectric Constant (1KHz):	3.08		
Dissipation Factor (1KHz):	0.003		

OPTICAL PROPERTIES @ 23°C:			
Spectral Transmission:	88% @ 800	nm	
	> 94% @ 880-1600	nm	
Refractive Index:	1.5657 @ 589	nm	

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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